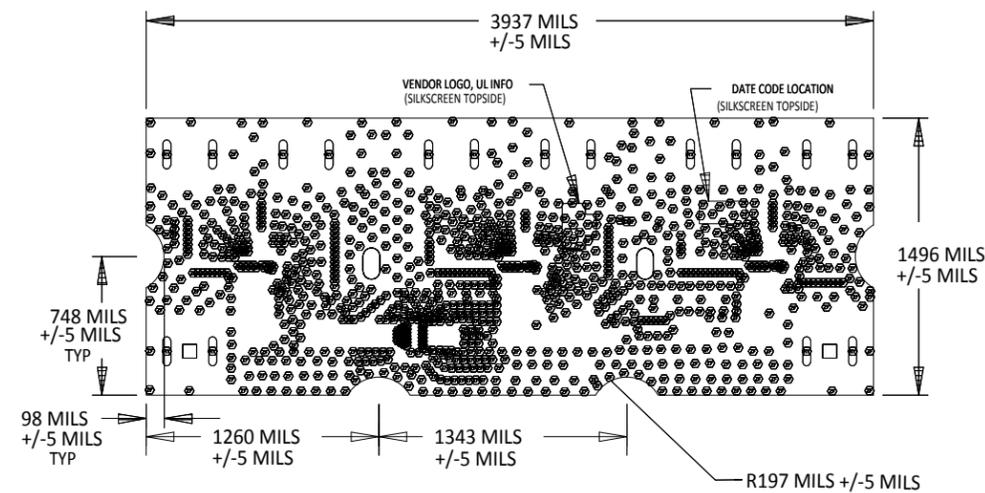
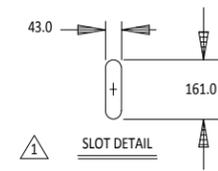


NOTES:

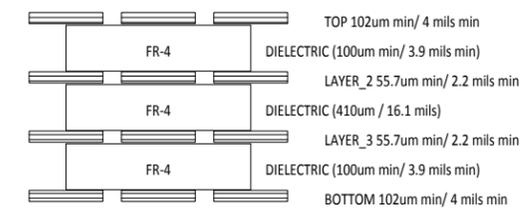
1. Specifications
 - 1.0 Fabricate per IPC-A-600 and IPC-6012 Class 3. UL Certification UL796.
 - 1.1 Manufacturability study- It is the responsibility of the supplier to conduct a thorough review of the artwork and media for manufacturability in the supplier's process compliance to all applicable specifications. Maxim must be advised in writing (in advance of manufacturing) of any changes, revisions, or corrections made or recommendations to ensure conformance to Maxim standards, and of any specifications that cannot be met.
 - 1.2 This drawing is to be used in conjunction with the provided gerber and drill data when applicable.
 - 1.3 All notes are "Unless Otherwise Specified."
2. Material
 - 2.0 Base material S1150G, Per IPC-4101/128 Tg >=150C.
 - 2.1 Copper clad high temperature FR4 Class epoxy glass Rated UL94V-0.
 - 2.2 Part must withstand, with no blistering, delamination, soldermask flaking or any other damages, 5 re-flow passes with maximum temperature of 260°C +/-5°C
 - 2.3 Td rating: >=325°C
 - 2.4 Z axis PTE <3.5%
3. Solder mask
 - 3.0 Solder mask PSR-4000 GEC50, both sides with (Green glossy) liquid photoimageable solder mask, 25um min thickness over trace.
4. Drilling and Routing
 - 4.0 All hole diameters are finished sizes.
 - 4.1 All holes to be +/-76um from true position unless otherwise specified.
 - 4.2 All hole diameters to be +/-76um unless otherwise specified.
 - 4.3 An NC drill file has been supplied - see drill table.
 - 4.4 For all routing and drilling operations at panel level, follow Panel DRWG indications instead of gerber data
 - 4.5 Slots in pads must follow "Slot Detail" drawing, which supersedes gerber file
5. Plating and Finishing
 - 5.0 Plate thru holes per IPC 6012 CLASS 3 with copper 25um min. thickness. Drill size dimension apply after plating.
 - 5.1 Finished coat exposed copper using OSP 0.2um to 0.4um
 - 5.2 Finished boards shall not have nicks, scratches, voids, exposed copper, poor plating, or misdrilled holes.
 - 5.3 Copper thickness per 'PCB CROSS SECTION'- indicated values are minimum guaranteed.
6. Silkscreen
 - 6.0 Silkscreen using white non-conductive epoxy or equivalent.
 - 6.1 No silkscreen allowed on exposed lands or in holes which are open on solder mask layers.
 - 6.2 Silkscreen must be a minimum of 3mm away from fiducial marks.
 - 6.3 No Silkscreen permitted on exposed Cu. pads. If silkscreen positioning tolerance in manufacturing may result in violating this rule, supplier is allowed to move Silkscreen and must notify customer about the change, submit final files for review and retrieve customer's approval on this item before proceeding with manufacturing.
 - 6.4 Registration to be +/- 203.2um and must pass peel test.
7. Electrical Test
 - 7.0 All boards shall be 100% electronically tested for opens/short at 50 volts.
 - 7.1 Apply test stamp in non-legend area on panel breakaway.
8. Cleanliness
 - 8.0 Boards shall be free of fiberglass dust or any other foreign material.
 - 8.1 Finished boards must conform to 0.01 MG/IN max NaCl ionic contamination as measured by the omega meter 600SMD. with sufficient surrounding material to prevent shipping damage.
9. Packaging
 - 9.0 There shall be a max of 25 panels per package, individually wrapped, and shipped in cardboard cartons
10. Bow and Twist
 - 10.0 Maximum allowable bow and twist per IPC-A600.
11. Inspection
 - 11.0 AOI of inner layers and ET test for outer layers required.
12. RoHS
 - 12.0 All materials used must be RoHS Compliant and Pb free as well and meet Maxim Spec# 10-0131: Control of Banned and Restricted Substances.
13. PCB fabrication must comply with Maxim document 10-0099 (Title: PCB INSPECTION/ASSEMBLY PROCEDURE).
14. Changes to original documentation
 - 14.0 If any changes are required from original documentation in order to fit the manufacturing process and avoid possible unwanted effects on the final product, the supplier will notify the customer about the changes and will send back all documentation for final approval

REVISIONS			
REV	DESCRIPTION	APPROVED	DATE
D	RELEASE		

DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	FINISHED_SIZE	TOLERANCE_DRILL	PLATED	QTY
⊙	8.0	+4.0/-4.0	PLATED	1086
⊘	43.0	+5.0/-5.0	PLATED	16
□	130.0	+5.0/-5.0	PLATED	2
○	169.0x91.0	+4.0/-4.0	PLATED	2



4 Layer Board -- All Cu Thickness is Final



TOTAL THICKNESS: 1031.2um (40.6 mils)
(MEASURED OVER Cu LANDS)

TOLERANCES UNLESS OTHERWISE SPECIFIED FRACTIONS: $\frac{XX}{YY}$ MILS: XX +/- 10, XXX +/- 5 ANGLES: +/- $\frac{XX}{YY}$		THE INFORMATION CONTAINED IN THIS DOCUMENT IS PROPRIETARY TO MAXIM. THE INFORMATION IN THIS DOCUMENT IS NOT TO BE SHOWN, REPRODUCED, OR DISCLOSED TO ANYONE OUTSIDE OF MAXIM WITHOUT PRIOR WRITTEN PERMISSION FROM MAXIM.			
MATERIAL: SEE NOTES		DRAWN BY: WHEWLEN DATE: 03/27/18		TITLE: FABRICATION DWG. MAX20800_DO_APPS_D	
FINISH: SEE NOTES		CHECKED BY: WHEWLEN DATE: 03/27/18 APPR. BY: ABJELETIC DATE: 03/27/18 APPR. BY: DATE:		SIZE: DRAWING NO. 35-900368-03-00 REV D	
		NOT TO SCALE		TEMPLATE REV 1.5 SHEET 1 OF 1	